

MX•COM, INC. MiXed Signal ICs

DATA BULLETIN

CMX654

V.23 TRANSMIT MODULATOR

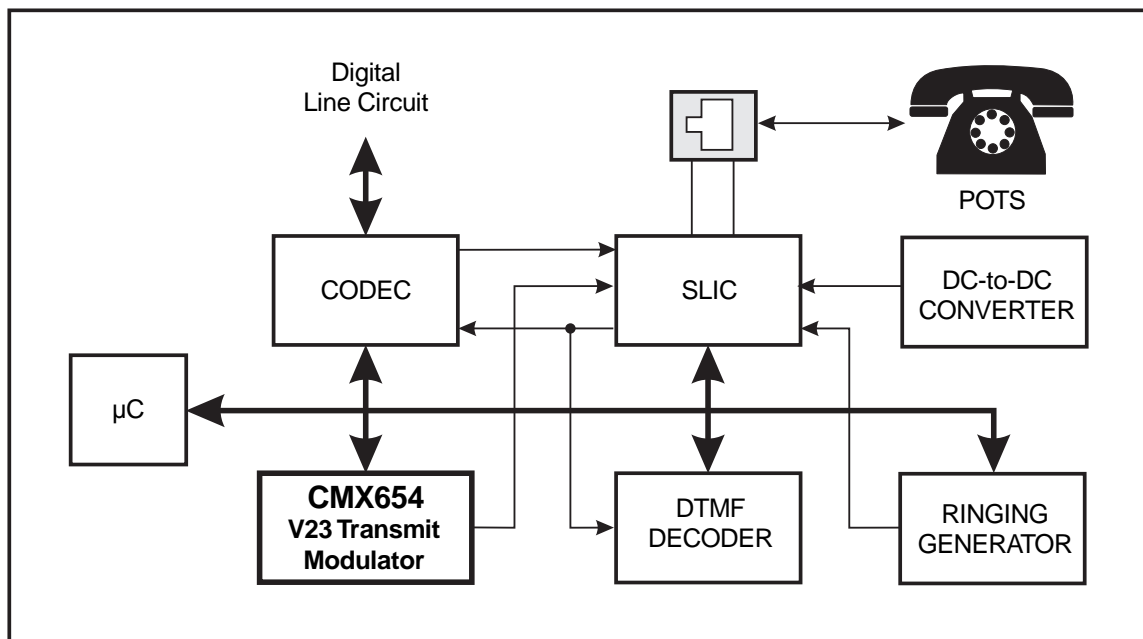
PRELIMINARY INFORMATION

Features

- 1200bits/sec, V.23 Transmit Modulator
- 3.0V to 5.5V Supply:
1mA typical at 3V
- Zero Power Mode:
1 μ A typical
- 1200bits/sec Tx Data Retiming
- 3.58MHz Xtal/Clock Rate
- Meets ITU and ETSI Specifications

Applications

- Caller ID generation for:
ISDN Terminal Adapters
Wireless Local Loop System
ISDN PABX Applications
Pair-Gain Systems
Public Switched Telephone Networks
Trunk Exchanges



The CMX654 is a low power integrated circuit, designed for the transmission of asynchronous 1200bits/sec data in accordance with ITU, V.23 and ETSI specifications.

The device incorporates an optional Tx data retiming function. This device may be operated so that only the mark or space tone is produced.

The CMX654 may be used in a wide range of telephone telemetry systems. With a low voltage requirement of 3.0V it is suitable for both portable terminal and line powered applications. A very low current 'sleep' mode (1 μ A typ.) and an operating current of 1mA typ. makes the CMX654 ideal for line powered applications.

This device requires a standard 3.58MHz Xtal/Clock rate and operates from a 3.0 to 5.5V supply. Available packages are: 16-pin SOIC (CMX654D4) and 16-pin PDIP (CMX654P3). Additional package styles may be available to meet specific design requirements.

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1 Block Diagram

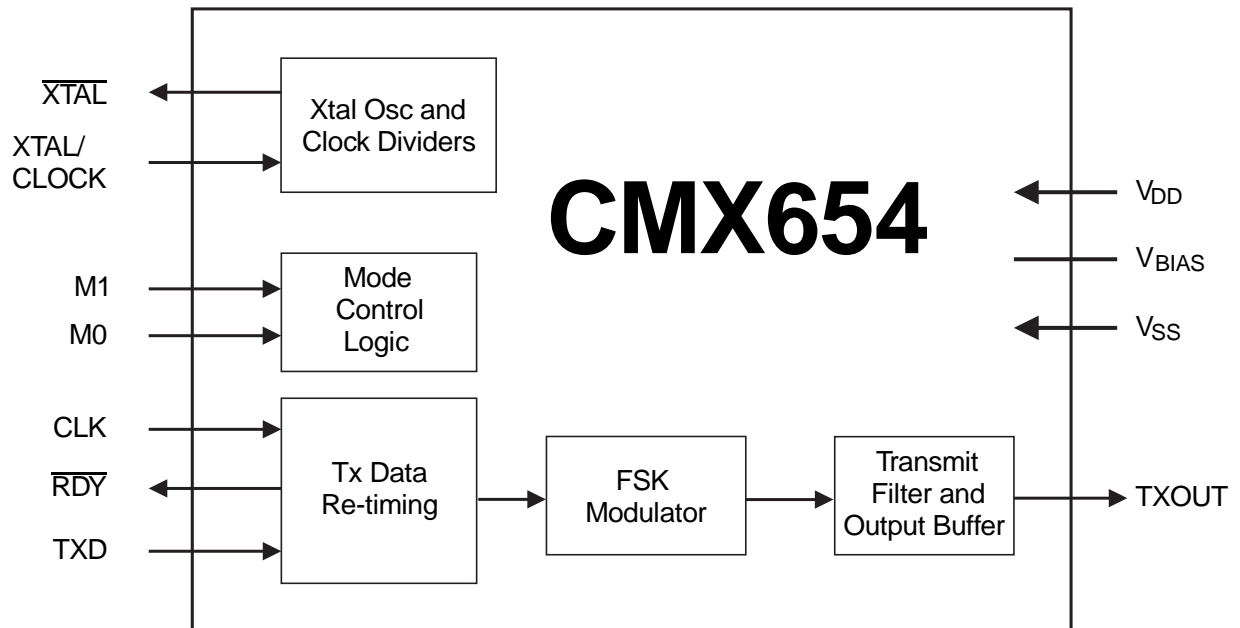


Figure 1: Block Diagram

2 Signal List

D4/P3	Signal		Description
Pin No.	Name	Type	
1	$\overline{\text{XTAL}}$	input	The output of the on-chip Xtal oscillator inverter.
2	XTAL/CLOCK	input	The input to the on-chip Xtal oscillator inverter.
3	M0	input	A logic level input for setting the mode of the device. See Section 4.2.
4	M1	input	A logic level input for setting the mode of the device. See Section 4.2.
5			Connect to V_{SS} .
6		N/C	No connection, do not connect to this pin.
7	TXOUT	output	The output of the FSK generator.
8	V_{SS}	Power	The negative supply rail (ground).
9	V_{BIAS}	output	Internally generated bias voltage, held at $V_{DD}/2$ when the device is not in 'Zero-Power' mode. Should be decoupled to V_{SS} by a capacitor mounted close to the device pins.
10	-	-	Connect to V_{DD} .
11	TXD	input	A logic level input for either the raw input to the FSK Modulator or data to be re-timed depending on the state of the M0, M1 and CLK inputs. See Section 4.3.
12	CLK	input	A logic level input which may be used to clock data bits into the Tx FSK Data Retiming block.
13	-	N/C	No connection, do not connect to this pin.
14	-	N/C	No connection, do not connect to this pin.
15	$\overline{\text{RDY}}$	output	"Ready for Tx data transfer" output of the on-chip data retiming circuit. This open-drain active low output may be used as an Interrupt Request/Wake-up input to the associated μC . An external pull-up resistor should be connected between this output and V_{DD} .
16	V_{DD}	Power	The positive supply rail. Levels and thresholds within the device are proportional to this voltage. Should be decoupled to V_{SS} by a capacitor mounted close to the device pins.

V_{DD} and V_{BIAS} decoupling is very important. It is recommended that the decoupling capacitors be placed so that connections between them and the device pins are as short as practicable.

Table 1: Signal List

3 External Components

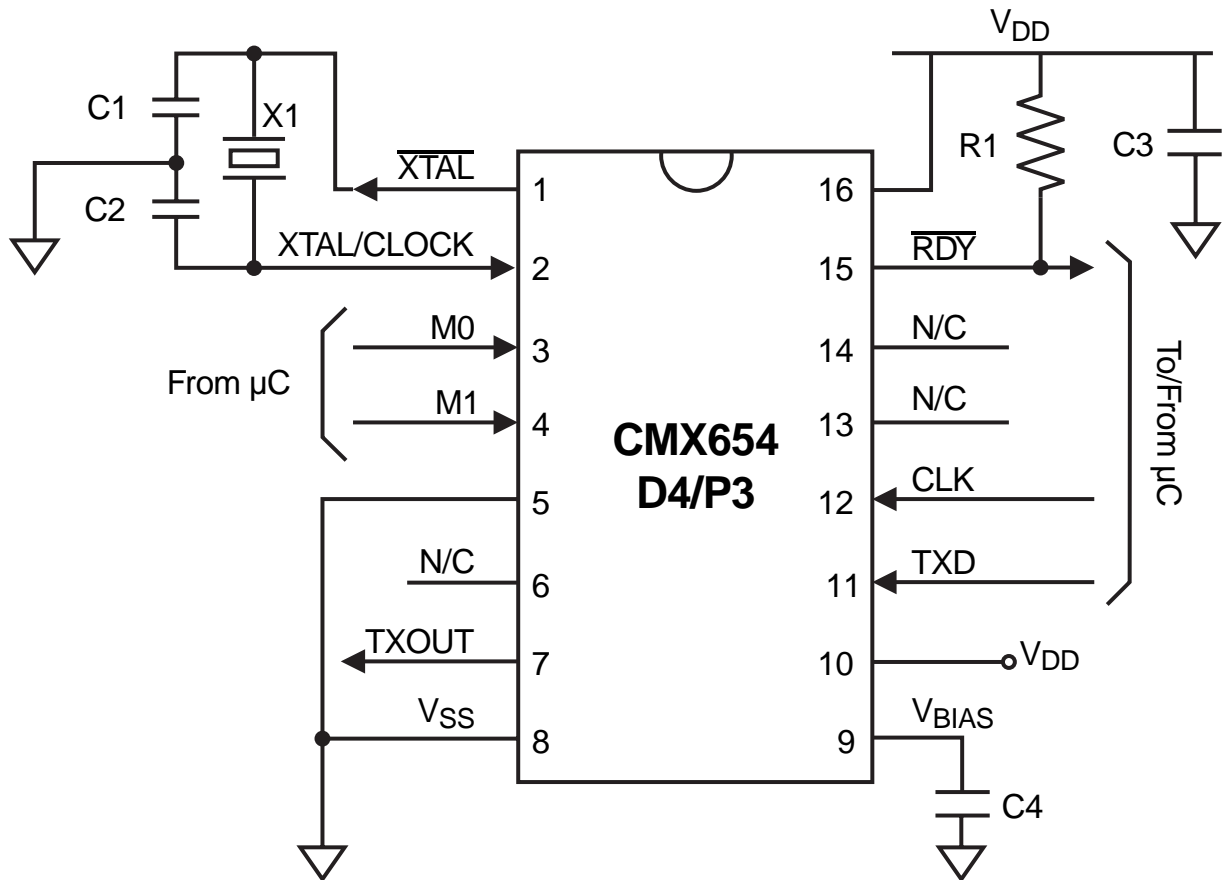


Figure 2: External Components

R1		100k Ω
C1, C2		18pF
C3		0.1 μ F
C4		0.1 μ F
X1	Note 1	3.579545MHz

Resistors $\pm 5\%$, capacitors $\pm 10\%$ unless otherwise stated

Table 2: External Components for Typical Application

External Components Notes:

1. A crystal frequency of $3.579545\text{MHz} \pm 0.1\%$ is required for correct FSK operation. For best results, a crystal oscillator design should drive the clock inverter input with signal levels of at least 40% of V_{DD} , peak-peak. Tuning fork crystals generally cannot meet this requirement. To obtain crystal oscillator design assistance, consult your crystal manufacturer. Operation of this device without a Xtal or Clock input may cause device damage.

4 General Description

4.1 Xtal Oscillator and Clock Dividers

Frequency and timing accuracy of the CMX654 is determined by a 3.579545MHz clock present at the XTAL/CLOCK pin. This may be generated by the on-chip oscillator inverter using the external components C1, C2 and X1 of Figure 2, or may be supplied from an external source to the XTAL/CLOCK input. If supplied from an external source, C1, C2 and X1 should not be fitted.

The on-chip oscillator is turned off in the 'Zero-Power' mode.

If the clock is provided by an external source, which is not always running, then the 'Zero-Power' mode must be set when the clock is not available. Failure to observe this rule may cause a significant rise in the supply current drawn by CMX654 as well as generating undefined states of the RDY output.

4.2 Mode Control Logic

The CMX654's operating mode is determined by the logic levels applied to the M0 and M1 input pins:

M1	M0	Tx Mode	Data Retime ^[1]
0	1	1200bits/sec	Tx
1	0	off	-
1	1	'Zero-Power'	-

[1] If enabled

In the 'Zero-Power' mode, power is removed from all internal circuitry. When leaving 'Zero-Power' mode there must be a delay of 20ms before any Tx data is passed to the device to allow the bias level, filters and oscillator to stabilize. On applying power to the device the mode must be set to 'ZP', i.e. M0=1, M1=1, until V_{DD} has stabilized.

4.3 FSK Modulator and Transmit Filter

These blocks produce a tone according to the TXD, M0 and M1 inputs as shown in the table below, assuming data retiming is not being used:

M1	M0	TXD = '0'	TXD = '1'
1	1	'Zero Power'	'Zero Power'
1	0	0Hz	0Hz ^[1]
0	1	2100Hz	1300Hz

[1] TXOUT held at approx. $V_{DD}/2$.

When modulated at the appropriate baud rates, the Transmit Filter and associated external components (see Section 5.1) limit the FSK out of band energy sent to the line in accordance with Figure 3 assuming that the signal on the line is at -6dBm or less.

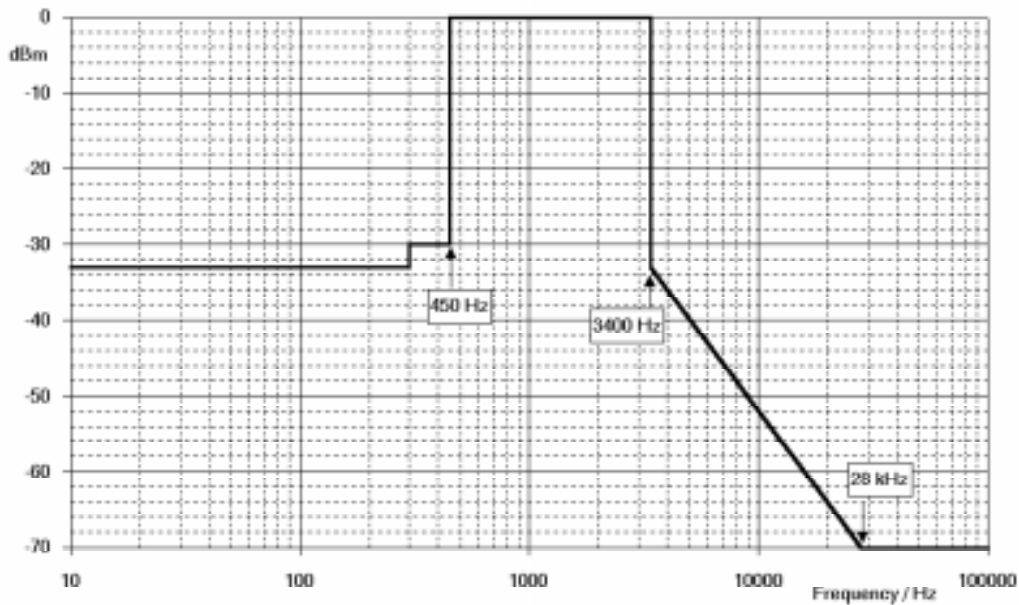


Figure 3: Tx Limits

4.4 Tx Data Retiming

The Data Retiming block, when enabled in 1200bits/sec transmit mode, requires the controlling μC to load 1 bit at a time into the device by a pulse applied to the CLK input. The timing of this pulse is not critical and it may easily be generated by a simple software loop. This facility removes the need for a UART in the μC without incurring an excessive software overhead.

The Tx re-timing circuit consists of two 1-bit registers in series, the input of the first is connected to the TXD pin and the output of the second feeds the FSK modulator. The second register is clocked by an internally generated 1200Hz signal and when this occurs the CLK input is sampled. If the CLK input is high the TXD pin directly controls the FSK modulator, if the CLK input is low the FSK modulator is controlled by the output of the second register and the $\overline{\text{RDY}}$ pin is pulled low. The $\overline{\text{RDY}}$ output is reset by a high level on the CLK input pin. A low to high change on the CLK input pin will latch the data from the TXD input pin into the first register ready for transfer to the second register when the internal 1200Hz signal next occurs.

So to use the retiming option the CLK input should be held low until the $\overline{\text{RDY}}$ output is pulled low. When the $\overline{\text{RDY}}$ pin goes low the next data bit should be applied at the TXD input and the CLK input pulled high and then low within the time limits set out in Figure 7.

To ensure synchronization between the controlling device and the CMX654 when entering Tx retiming mode, the TXD pin must be held at a constant logic level from when the CLK pin is first pulled low to the end of loading in the second retimed bit. Similarly when exiting Tx retiming mode the TXD pin should be held at the same logic level as the last retimed bit for at least 2 bit times after the CLK line is pulled high.

If the data retiming facility is not required, the CLK input to the CMX654 should be kept high at all times. The asynchronous data to the FSK modulator will then be connected directly to the TXD input pin. This is illustrated in Figure 4.

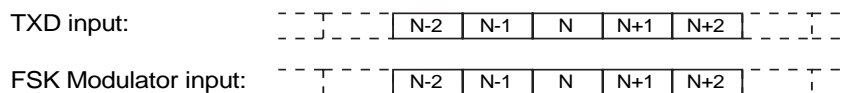


Figure 4: FSK Operation without Tx Data Retiming (CLK always high)

5 Application Notes

5.1 Line Interface

The signals on the telephone line are not suitable for direct connection to the CMX654. A Line Interface circuit is necessary to:

- Provide high voltage and DC isolation
- Provide the low impedance drive necessary for the line
- Filter the Tx and Rx signals

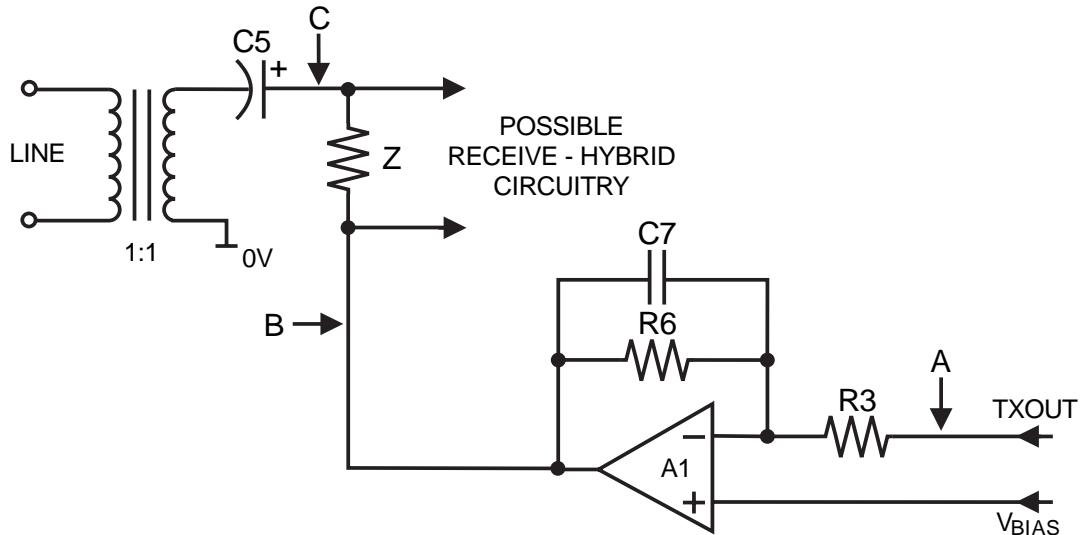


Figure 5: Line Interface Circuit

R3	Note 3	C5	22 μ F (\pm 20%)
R6	100k Ω	C7	330pF

Resistors \pm 1%, capacitors \pm 10% unless otherwise stated.

Notes:

1. The component(s) 'Z' between points B and C should match the line impedance.
2. Device A1 must be able to drive 'Z' and the line.
3. R3: The levels in dB (relative to a 775mV_{RMS} signal) at 'A', 'B' and 'C' in the line interface circuit are:

$$'A' = 20\text{Log}(V_{DD}/5)$$

$$'B' = 'A' + 20\text{Log}(100\text{k}\Omega/R3)$$

$$'C' = 'B' - 6$$

V _{DD}	'A'	R3	'B'	'C'
3.3V	-3.6dB	100k Ω	-3.6dB	-9.6dB
5.0V	0dB	150k Ω	-3.5dB	-9.5dB

6 Performance Specification

6.1 Electrical Performance

6.1.1 Absolute Maximum Ratings

Exceeding these maximum ratings can result in damage to the device.

	Min.	Max.	Units
Supply ($V_{DD} - V_{SS}$)	-0.3	7.0	V
Voltage on any pin to V_{SS}	-0.3	$V_{DD} + 0.3$	V
Current into or out of:			
V_{DD}	-30	30	mA
V_{SS}	-30	30	mA
Any other pin	-20	20	mA
D4 / P3 Package			
Total Allowable Power Dissipation at $T_{AMB} = 25^{\circ}\text{C}$		800	mW
Derating above 25°C		13	mW/ $^{\circ}\text{C}$ above 25°C
Storage Temperature	-55	125	$^{\circ}\text{C}$
Operating Temperature	-40	85	$^{\circ}\text{C}$

6.1.2 Operating Limits

Correct operation of the device outside these limits is not implied.

	Notes	Min.	Max.	Units
Supply ($V_{DD} - V_{SS}$)		3.0	5.5	V
Operating Temperature		-40	85	$^{\circ}\text{C}$
Xtal Frequency	1	3.575965	3.583125	MHz

Notes:

1. A Xtal frequency of 3.579545MHz \pm 0.1% is required for correct FSK operation.

6.1.3 Operating Characteristics

For the following conditions unless otherwise specified:

$V_{DD} = 3.0V$ at $T_{AMB} = 25^{\circ}C$ and $V_{DD} = 3.3V$ to $5.5V$ at $T_{AMB} = -40$ to $+85^{\circ}C$,

Xtal Frequency = $3.579545MHz \pm 0.1\%$, 0dBV corresponds to $1.0V_{RMS}$,

0dBm corresponds to $775mV_{RMS}$ into 600Ω .

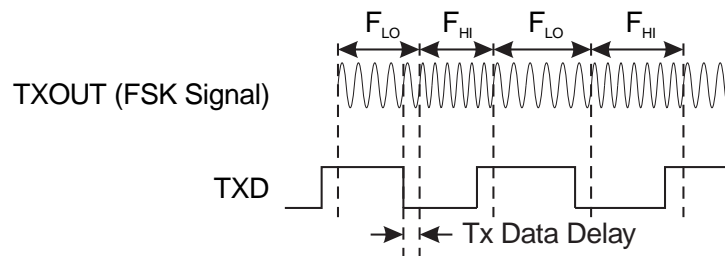
	Notes	Min.	Typ.	Max.	Units
DC Parameters					
I_{DD} (M0='1', M1='1')	1, 2		1		μA
I_{DD} (M0 or M1='0') at $V_{DD} = 3.0V$	1		1.0	1.25	mA
I_{DD} (M0 or M1='0') at $V_{DD} = 5.0V$	1		1.7	2.5	mA
Logic '1' Input Level		70%			V_{DD}
Logic '0' Input Level				30%	V_{DD}
Logic Input Leakage Current ($V_{IN} = 0$ to V_{DD}), Excluding XTAL/CLOCK Input		-1.0		1.0	μA
Output Logic '1' Level ($I_{OH} = 360\mu A$)		$V_{DD}-0.4$			V
Output Logic '0' Level ($I_{OL} = -360\mu A$)				0.4	V
\overline{RDY} Output 'off' State Current ($V_{OUT} = V_{DD}$)				1.0	μA
FSK Retiming					
Tx Data Rate		1194		1206	Baud
FSK Modulator					
TXOUT Level	3	-1.0	0	1.0	dB
Twist (Mark Level WRT Space Level)		-2.0	0	2.0	dB
Tx 1200bits/sec (M1='0', M0='1').					
Bit Rate		0	1200	1212	Baud
Mark (Logical 1) Frequency		1297		1303	Hz
Space (Logical 0) Frequency		2097		2103	Hz
XTAL/CLOCK Input					
'High' Pulse Width	4	100			ns
'Low' Pulse Width	4	100			ns

Operating Characteristics Notes:

1. At $25^{\circ}C$, not including any current drawn from the CMX654 pins by external circuitry other than X1, C1 and C2.
2. TXD and CLK inputs at V_{SS} , M0 and M1 inputs at V_{DD} .
3. Relative to $775mV_{RMS}$ at $V_{DD} = 5.0V$ for load resistance greater than $40k\Omega$.
4. Timing for an external input to the XTAL/CLOCK pin.

6.2 Timing

Data and Mode Timing	Min.	Typ.	Max.	Units
Delay to reliable data at TXOUT after ZP to Tx mode change			20.0	ms
Data Retiming Disabled (reference Figure 6)				
Tx Data Delay (TXD to TXOUT)		0.1		ms
Data Retiming Enabled (reference Figure 7)				
t_D = Internal CMX654 delay			1	μ S
t_{CH} = CLK High time	1			μ S
t_R = RDY low to CLK going low			800	μ S
t_S = Data Set-up time	1			μ S
t_H = Data Hold time	1			μ S



Note: M0 and M1 are preset and stable. F_{LO} and F_{HI} are the two FSK signaling frequencies.

Figure 6: TXD to TXOUT Delay time

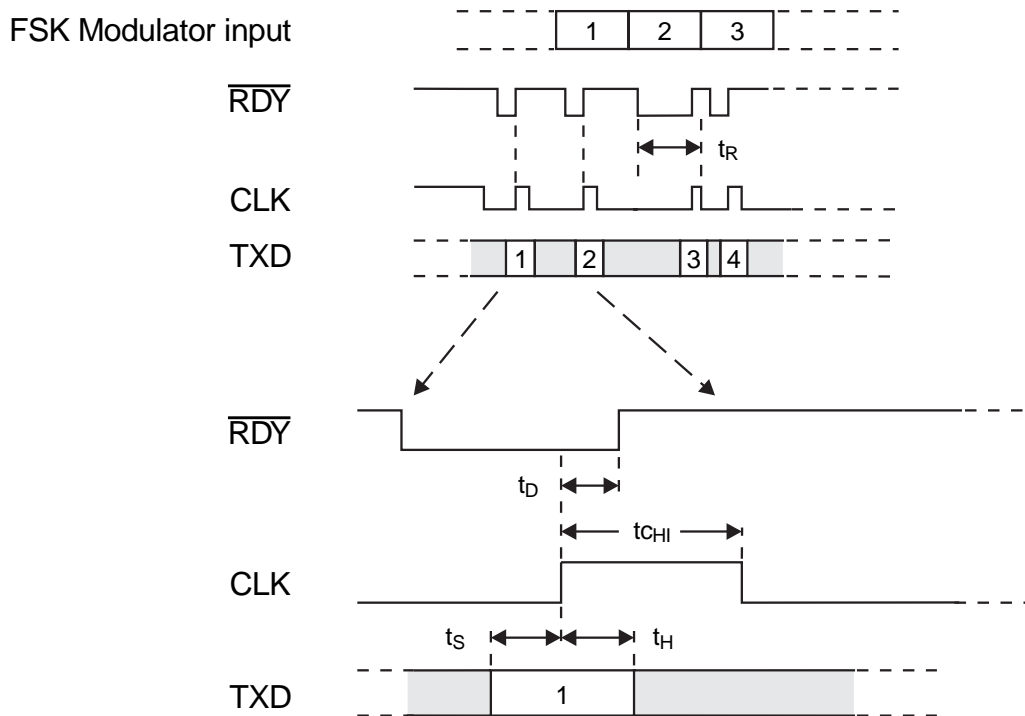


Figure 7: FSK Operation with Tx Data Retiming

6.3 Packaging

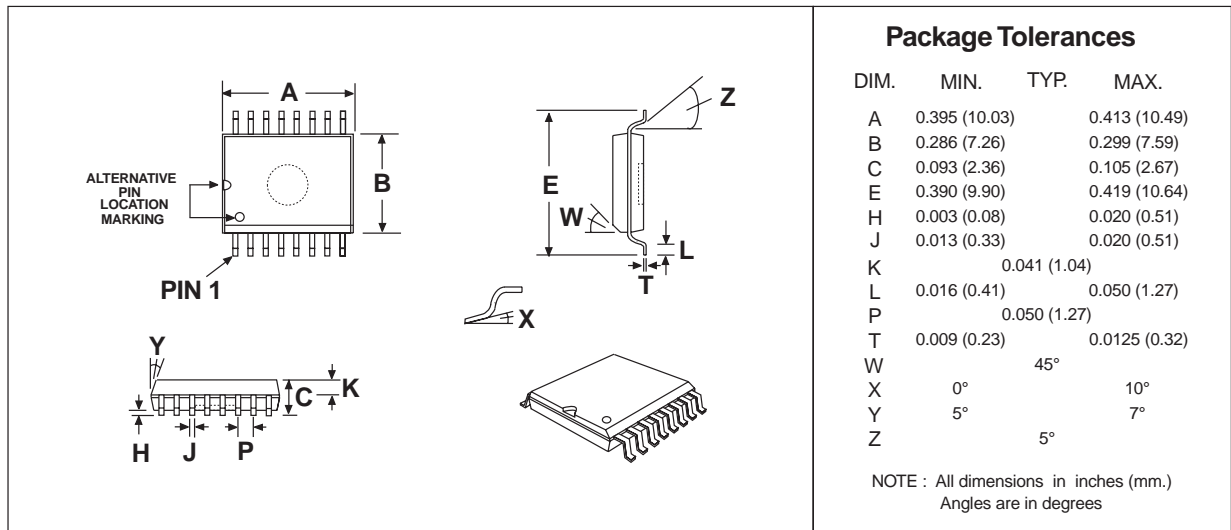


Figure 8: 16-pin SOIC (D4) Mechanical Outline: *Order as part no. CMX654D4*

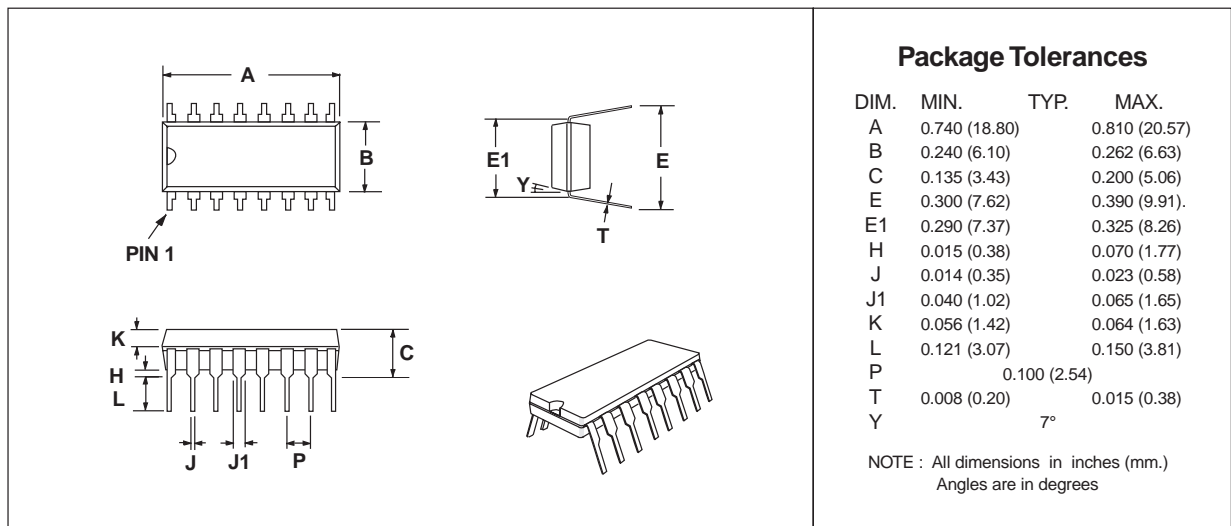


Figure 9: 16-pin PDIP (P3) Mechanical Outline: *Order as part no. CMX654P3*